

# 无卤无铅焊锡膏

减少焊接部的气孔

NH系列, LH系列

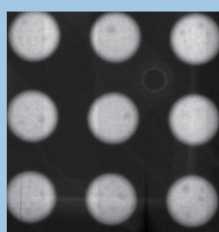
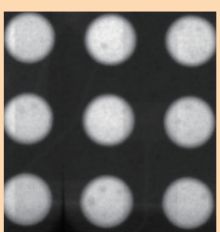
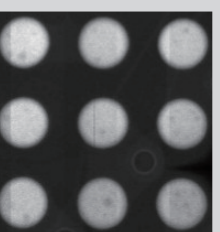
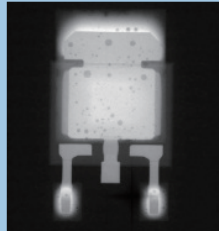


## 产品列表

商品名	卤素量	Cl %*	Br %*
		PS31BR-600-NH5	完全无卤
PS31BR-600A-LH1	IPC标准无卤	700ppm	700ppm
0402封装 PS31BR-750-NH3	完全无卤	0ppm	0ppm

\* 助焊剂燃烧法

## 气孔量少, 润湿性良好

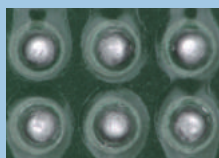
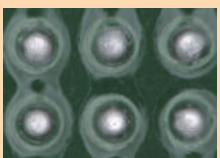
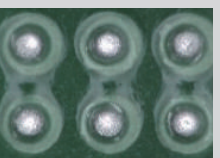
### 气孔测试

	PS31BR-600-NH5	PS31BR-600A-LH1	以往品 (含卤)
BGA (0.8mm间距)			
下面电极部位 (功率晶体管)			

#### 测试条件

- 回流条件: 空气回流
- 印刷厚度: 150μm

### 融锡性测试

	PS31BR-600-NH5	PS31BR-600A-LH1	以往品 (含卤)
Φ0.25mm 焊盘			

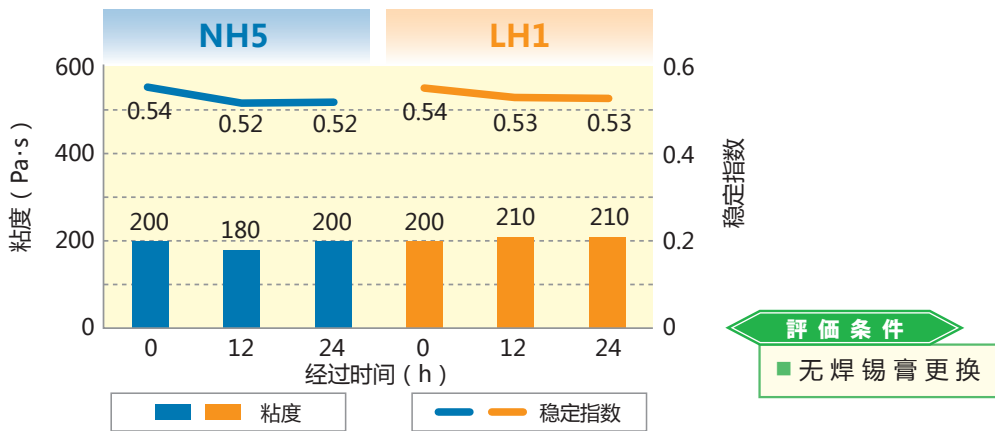
#### 测试条件

- 回流条件: 空气回流
- 印刷厚度: 150μm

助焊剂优化配比, 得到与含卤产品同等的焊接效果

## 良好的粘度稳定性

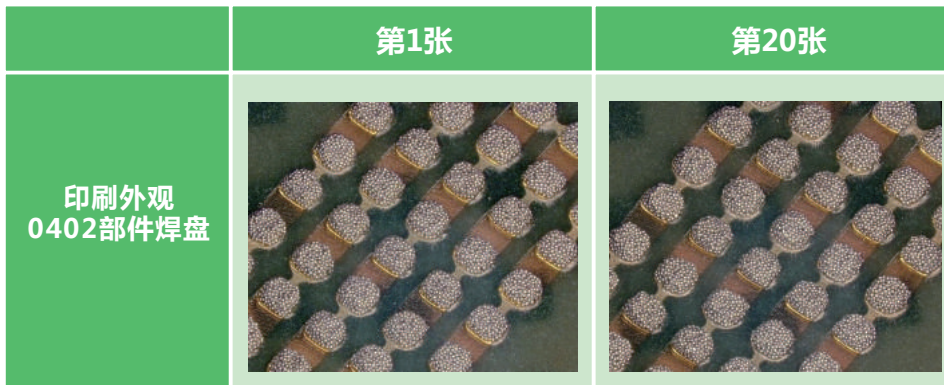
粘度与稳定指数的变化



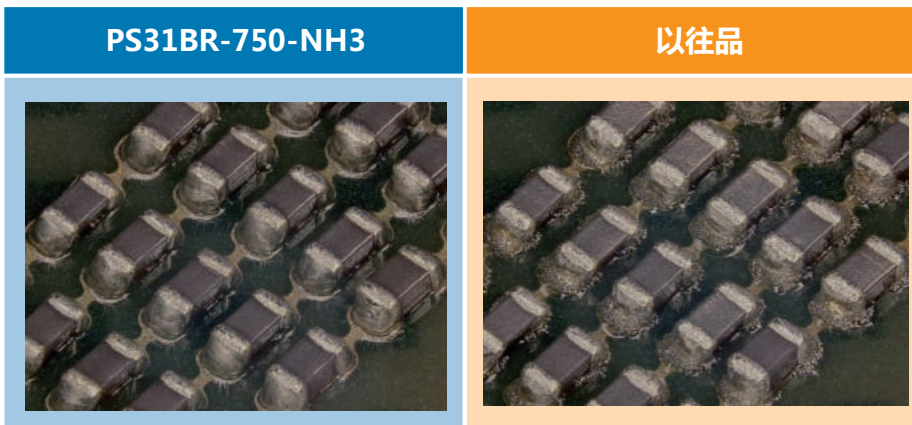
24小时连续印刷后粘性变化小

## 对应0402部件的封装 (PS31BR-750-NH3)

焊锡膏印刷后外观



0402部件封装



0402部件封装处也得到良好的融锡性